

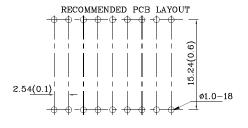
Part Number: XAUR14C2

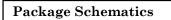
13.8mm (0.543") 14 SEGMENT DUAL DIGIT ALPHANUMERIC DISPLAY

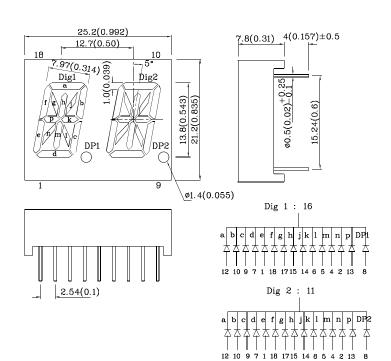
Features

- Low power consumption
- \bullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant









Notes: 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted. 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	160	mA	
Power Dissipation	\mathbf{P}_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	$V_{\rm F}$	V _F 1.9	
Forward Voltage (Max.) (I _F =10mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	627*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$ riangle\lambda$	45	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	$_{\rm pF}$

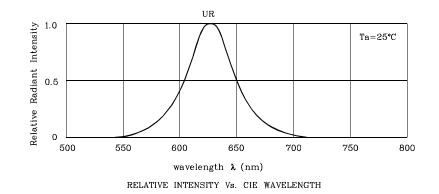
Part Number	Emitting Color	Emitting Material	Luminous CIE127 (I _F =10m	-2007*	Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XAUR14C2	Red	GaAsP/GaP	2200 900*	$5990 \\ 1790*$	627*	Common Cathode ,Rt. Hand Decimal.

 ${\rm *Luminous\ intensity\ value\ and\ wavelength\ are\ in\ accordance\ with\ CIE127-2007\ standards.}$

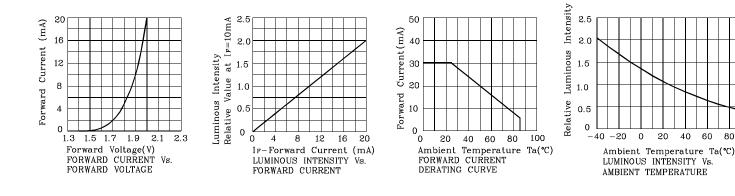
Mar 01,2014

XDSA1164 V6-X Layout: Maggie L.

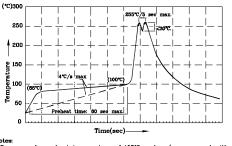




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Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



nmend pre-heat temperature of 105°C or less (as measured with a nocouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 280°C wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec 1. Rec the wave 2.Peak

 Peak wave soldering temperature between max).
Do not apply stress to the epoxy result.
Pixtures should not incur stress on the during soldering process.
SAC 305 solder alloy is recommended.
No more than one wave soldering pass. while the temperature is ab component when mounting sin the

Remarks:

If special sorting is required (e.g. binning based on forward voltage,

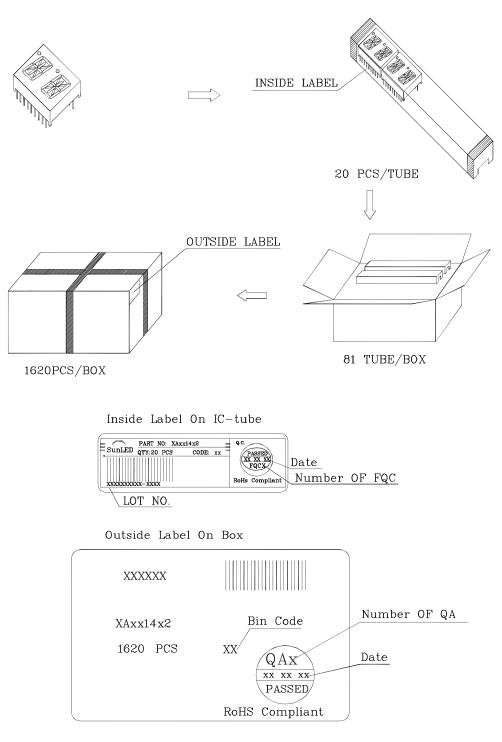
luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V
- Note: Accuracy may depend on the sorting parameters.

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- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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